



## Product Change Notification / LIAL-24K0XB344

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### Date:

26-Mar-2021

### Product Category:

Automotive LED Drivers, Backlight LED Drivers, Battery Management and Fuel Gauges - Battery Chargers, Clock and Timing - Clock and Data Distribution, Clock and Timing - Clock Generation, General Purpose LED Drivers, Hot Swap Controller, Linear Comparators, Linear Op Amps, Linear Regulators, Power Management - Power Switches, Power Management - PWM Controllers, Power Management - System Supervisors/Voltage Detectors, Power MOSFET Drivers, Switching Regulators, Temperature Sensors, Voltage References, Wireless IC

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4477 Final Notice Implement additional cover tape, carrier tape and plastic reel material supplier for selected Micrel products available in 3L, 5L, 6L and 8L SOT23, 5L and 6L TSOP and 8L SOIC packages at STAR assembly site.

### Affected CPNs:

[LIAL-24K0XB344\\_Affected\\_CPN\\_03262021.pdf](#)

[LIAL-24K0XB344\\_Affected\\_CPN\\_03262021.csv](#)

### Notification Text:

**PCN Status:**Final notification.

#### PCN Type:

Manufacturing Change

#### Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Implement additional cover tape, carrier tape and plastic reel material supplier for selected Micrel products available in 3L, 5L, 6L and 8L SOT23, 5L and 6L TSOP and 8L SOIC packages at STAR assembly site.

**Pre Change:** Using CPAK carrier tape, cover tape and plastic reel material

**Post Change:** Using CPAK carrier tape, cover tape and plastic reel material or 3M carrier tape and cover tape material or U-PAK carrier tape and cover tape material and LPP plastic reel material.

**Pre and Post Change Summary:**

NOTE: See attached Packing Pre and Post Changes for the changes of the following.

|                                        |              |                | Pre Change                                                             | Post Change                                                            |             |                |              |
|----------------------------------------|--------------|----------------|------------------------------------------------------------------------|------------------------------------------------------------------------|-------------|----------------|--------------|
| Packing location                       |              |                | Stars Microelectronics (Thailand) Public Company Limited<br><br>(STAR) | Stars Microelectronics (Thailand) Public Company Limited<br><br>(STAR) |             |                |              |
| Packing Supplier                       |              |                | CPAK<br>note1 and note2                                                | CPAK<br>note1 and note2                                                | 3M<br>note1 | U-PAK<br>note1 | LPP<br>note2 |
| SOT23-3/5/6/8L and TSOT-5L/6L packages | Carrier Tape |                | Minor dimensional changes. See pre and post change comparison.         |                                                                        |             |                |              |
|                                        | Cover tape   | Sealing Method | Heat Seal                                                              |                                                                        | Heat Seal   |                | Heat Seal    |
|                                        |              | Dimensions     | Minor dimensional changes. See pre and post change comparison.         |                                                                        |             |                |              |
|                                        | Plastic reel | Color          | Blue                                                                   |                                                                        | Blue        |                |              |
|                                        |              | Dimensions     | Minor dimensional changes. See pre and post change comparison.         |                                                                        |             |                |              |
| SOIC 8L package                        | Carrier Tape |                | Minor dimensional changes. See pre and post change comparison          |                                                                        |             |                |              |
|                                        | Cover tape   | Sealing Method | Heat Seal                                                              |                                                                        | Heat Seal   |                | Heat Seal    |
|                                        |              | Dimensions     | Minor dimensional changes. See pre and post change comparison          |                                                                        |             |                |              |

\*Note1: Carrier Tape and Cover tape supplier

\*Note 2: Reel supplier

**Impacts to Data Sheet:**None

**Change Impact:**

None

**Reason for Change:**

Due to unforeseen business conditions and to improve on-time delivery performance, Microchip has qualified 3M and UPAK as an additional cover tape and carrier supplier and LPP as additional reel supplier at STAR assembly site effective immediately.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:** December 2, 2020 (date code: 2049)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

|                               | December 2020 |    |    |    |    |
|-------------------------------|---------------|----|----|----|----|
| Workweek                      | 49            | 50 | 51 | 52 | 53 |
| Final PCN Issue Date          | X             |    |    |    |    |
| Estimated Implementation Date | X             |    |    |    |    |

**Method to Identify Change:** Traceability code

**Qualification Report**

Not applicable

**Revision History:**

**December 2, 2020:** Issued final notification. Provided estimated first ship date to be on December 2, 2020. **December 16, 2020:** Re-issued final notification to update the time-table summary to remove the Qual report availability date as this is not applicable and to update the post change in the pre and post change summary table to add note2 to CPAK packing supplier. **March 26, 2021:** Re-issued final notification to update the typo on cover tape thickness of CPAK packing supplier in the pre and post change comparison attachment

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN LIAL-24K0XB344 Pre and Post change comparison -rev1.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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